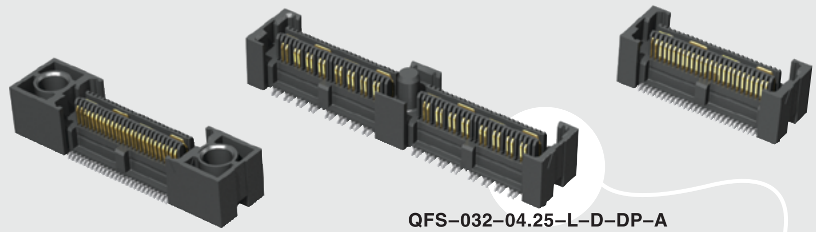


(0.635 mm) .025"

QFS SERIES

RUGGED GROUND PLANE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QFS

Insulator Material:
Liquid Crystal Polymer
Contact & Ground
Plane Material:
Phosphor Bronze
Plating:
Au over 50 µ" (1.27 µm) Ni
(Tin on Ground Plane Tail)
Current Rating:
Contact:
2.6 A per pin
(2 pins powered)
Ground Plane:
15.7 A per ground plane
(1 ground plane powered)
Voltage Rating:
300 VAC mated with QMS
Operating Temp:
-55 °C to +125 °C
RoHS Compliant:
Yes

PROCESSING

Lead–Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (026-078)
Board Stacking:
For applications requiring more than two connectors per board contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

STANDARDS

- SUMIT™
- PCI/104-Express™
- PCI/104-Express™ OneBank

Visit www.samtec.com/standards for more information.

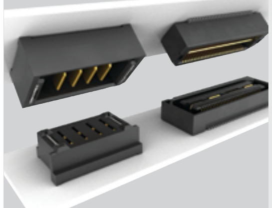
Note:
Some lengths, styles and options are non-standard, non-returnable.

Board Mates:
QMS

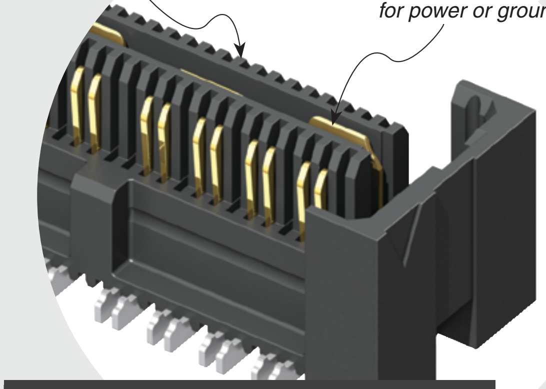
Cable Mates:
6QCD

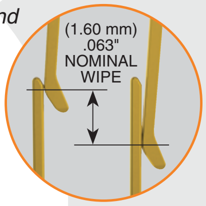
Standoffs:
SO, JSOM

POWER/SIGNAL APPLICATION



Compatible with UMPT/UMPS for flexible two-piece power/signal solutions





HIGH-SPEED CHANNEL PERFORMANCE

QMS-DP/QFS-DP @ 10 mm Mated Stack Height

Rating based on Samtec reference channel.
For full SI performance data visit Samtec.com or contact SIG@samtec.com

25 Gbps

ALSO AVAILABLE (MOQ Required)

- Other platings
- Without PCB Alignment Pins
- Hot Pluggable
- 4 banks (104 -SE, 64 -DP)

QFS – PINS PER ROW NO. OF PAIRS – LEAD STYLE – PLATING OPTION – TYPE – A – OTHER OPTION

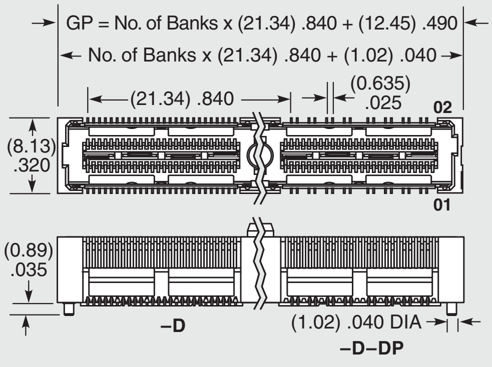
PINS PER ROW / NO. OF PAIRS
–026, –052, –078
(52 total pins per bank = –D)
–016, –032, –048
(16 pairs per bank = –D–DP)

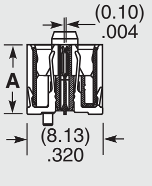
LEAD STYLE
Specify LEAD STYLE from chart

PLATING OPTION
–L
(–04.25 lead style only)
= 10 µ" (0.25 µm) Gold on Signal Pins and Ground Plane
(Tin on Signal Pin tails, and Ground Plane tails)
–SL
(–06.25 lead style only)
= 10 µ" (0.25 µm) Gold on Signal Pins and Ground Plane
(Tin on Signal Pin tails, and Ground Plane tails)

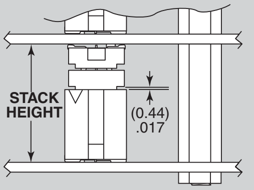
TYPE
–D
= Single-Ended
–D–DP
= Differential Pair
(–04.25 lead style only)

OTHER OPTION
–GP
= Guide Holes
(–04.25 lead style only)





APPLICATION



Requires Standoff SO-1524-03-01-01-L or JSOM-1524-02 for 15.24 mm or SO-2215-02-01-01-L for 22 mm board spacing. Connectors designed to not fully seat when mated.

MATED HEIGHT*				
LEAD STYLE	A	QMS LEAD STYLE		
		–05.75	–06.75	–09.75
–04.25	(7.44) .293	10 mm	11 mm	14 mm
–06.25	(9.42) .371	12 mm	13 mm	16 mm

*Processing conditions will affect mated height. See SO Series for board space tolerances.

INDUSTRY STANDARD	INTERCONNECTS			
	TERMINAL	SOCKET	BANKS	STACK HEIGHT
SUMIT™	ASP-129637-01	ASP-129646-01	1	15.24 mm
PCI/104-Express™	ASP-129637-03	ASP-129646-03	3	15.24 mm
PCI/104-Express™	ASP-129637-13	ASP-129646-22	1	15.24 mm
PCI/104-Express™	ASP-142781-01	ASP-129646-01	1	22 mm
PCI/104-Express™	ASP-142781-02	ASP-129646-02	2	22 mm
PCI/104-Express™	ASP-142781-03	ASP-129646-03	3	22 mm